

ABSTRACT

METHOD OF DICING THIN SEMICONDUCTOR SUBSTRATES

5

A method of dicing a plurality of integrated devices included in a semiconductor substrate using laser energy comprises the steps of directing a first laser beam onto a cutting line along the substrate to ablate a portion of the substrate located along the cutting line to be diced, the portion of the

10 substrate that is ablated forming a recast material adjacent to the cutting line of the substrate that has been diced. A second laser beam is directed onto another portion of the substrate adjacent to the cutting line to conduct heat processing of the recast material formed adjacent to the cutting line.

15 (FIG. 4)